



**Notes:**

1. All dimensions are in mm. Angles in degrees.
2. Coplanarity applies to the exposed pad as well as the terminals.
3. Refer JEDEC MO-287.
4. Thermal pad soldering area (mesh stencil design is recommended)



DATE: 12/03/13

DESCRIPTION: 8-contact, Super Thin DFN, X2DFN

PACKAGE CODE: XDA

DOCUMENT CONTROL #: PD-2176

REVISION: --